



Shin-Etsu Silicones of America, Inc.
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FE-401U

Product Description

Shin-Etsu FE-401 U is a fluorosilicone/silicone blend. It is designed to process well in molding applications.

Product Features

- Good fuel and oil resistance.
- Usable over a broad temperature range.

Typical Applications

- Chemical resistant packings and seals.
- Oil and fuel resistant seals, O rings, diaphragms for automotive.
- Heat and cold resistant packings, connectors, gaskets for aeronautical applications.

Packaging Information

44lb or 88lb Box|50lb Box

Typical Properties

Type of HCR	Fluorosilicone
Cure Agent	DCP-40
Durometer	48
Tensile Strength (psi)	1600
Elongation (%)	540
Specific Gravity	1.31
Tear Die B (ppi)	200
Compression Set (%)	20
Comp. Set Time (hours)	22
Comp. Set Temp. (°C)	205
Comp. Set Temp. (°F)	401
Press Cure/Post Cure	Post
Post Cure Time (hours)	4
Post Cure Temp. (°C)	220
Post Cure Temp. (°F)	428

Note: Values are not for specification purposes.

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